



# DMT10H014LSS

### **100V N-CHANNEL ENHANCEMENT MODE MOSFET**

# **Product Summary**

BV <sub>DSS</sub>	R <sub>DS(ON)</sub> Max	Ι <sub>D</sub> T <sub>A</sub> = +25°C
100V	15mΩ @ V <sub>GS</sub> = 10V	8.9A
	$18m\Omega @ V_{GS} = 6.0V$	7.9A

# **Description and Applications**

This new generation N-Channel Enhancement Mode MOSFET is designed to minimize  $R_{DS(ON)}$ , yet maintain superior switching performance. This device is ideal for use in notebook battery power management and load switch.

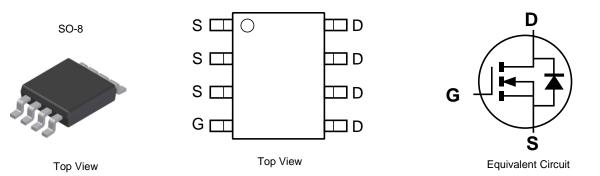
- Backlighting
- Power Management Functions
- DC-DC Converters

# **Features and Benefits**

- 100% Unclamped Inductive Switch (UIS) Test in Production
- High Conversion Efficiency
- Low R<sub>DS(ON)</sub> Minimizes On-State Losses
- Low Input Capacitance
- Fast Switching Speed
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

# **Mechanical Data**

- Case: SO-8
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections Indicator: See Diagram
- Terminals: Finish Matte Tin Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 (@)
- Weight: 0.074 grams (Approximate)



# Ordering Information (Note 4)

Part Number	Case	Packaging
DMT10H014LSS-13	SO-8	2,500/Tape & Reel

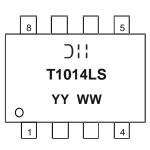
Notes: 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.

2. See http://www.diodes.com/quality/lead\_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.

3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

# **Marking Information**



);; = Manufacturer's Marking T1014LS = Product Type Marking Code YYWW = Date Code Marking YY or  $\overrightarrow{YY}$  = Year (ex: 16 = 2016) WW = Week (01 to 53)



## Maximum Ratings (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic Drain-Source Voltage Gate-Source Voltage			Symbol	Value	Unit V V
			V <sub>DSS</sub>	100	
			V <sub>GSS</sub>	±20	
Continuous Drain Current (Note 6) $V_{GS}$ = 10V	Steady State	$T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$	ID	8.9 7.1	А
Maximum Continuous Body Diode Forward Current (Note 6)			ls	3	A
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)			I <sub>DM</sub>	54	A
Avalanche Current, L = 3mH			I <sub>AS</sub>	7.5	A
Avalanche Energy, L = 3mH			E <sub>AS</sub>	85	mJ

# Thermal Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Total Power Dissipation (Note 5)	PD	1.2	W
Thermal Resistance, Junction to Ambient (Note 5)	R <sub>0JA</sub>	100	°C/W
Total Power Dissipation (Note 6)	PD	1.67	W
Thermal Resistance, Junction to Ambient (Note 6)	R <sub>0JA</sub>	75	°C/W
Thermal Resistance, Junction to Case (Note 6)	R <sub>0JC</sub>	12	°C/W
Operating and Storage Temperature Range	T <sub>J,</sub> T <sub>STG</sub>	-55 to +150	°C

# Electrical Characteristics (T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 7)							
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	100	_	_	V	$V_{GS} = 0V, I_D = 1mA$	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	—	-	1	μA	$V_{DS} = 80V, V_{GS} = 0V$	
Gate-Source Leakage	IGSS	—	_	±100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 7)							
Gate Threshold Voltage	V <sub>GS(TH)</sub>	1.4	2	3	V	$V_{DS} = V_{GS}$ , $I_D = 250 \mu A$	
		—	11.5	15		$V_{GS} = 10V, I_D = 20A$	
Static Drain-Source On-Resistance	R <sub>DS(ON)</sub>	—	15	18	mΩ	$V_{GS} = 6V, I_D = 20A$	
		—	17.5	25		$V_{GS} = 4.5V, I_{D} = 5A$	
Diode Forward Voltage	V <sub>SD</sub>	_	0.9	1.3	V	$V_{GS} = 0V, I_{S} = 20A$	
DYNAMIC CHARACTERISTICS (Note 8)							
Input Capacitance	Ciss	—	1871		pF	$V_{DS} = 50V, V_{GS} = 0V$ f = 1MHz	
Output Capacitance	Coss	—	261	_			
Reverse Transfer Capacitance	C <sub>rss</sub>	—	7	_			
Gate Resistance	R <sub>G</sub>	_	0.75	_	Ω	$V_{DS} = 0V, V_{GS} = 0V, f = 1MHz$	
Total Gate Charge	Qg	—	33.3	_			
Gate-Source Charge	Q <sub>gs</sub>	_	6.9	_	nC	$V_{DD} = 50V, I_D = 10A,$ $V_{GS} = 10V$	
Gate-Drain Charge	Q <sub>gd</sub>	_	5.1	-			
Turn-On Delay Time	t <sub>D(ON)</sub>	_	6.5	_			
Turn-On Rise Time	t <sub>R</sub>	_	7		ns	$\label{eq:VDD} \begin{split} V_{DD} &= 50 V, \ V_{GS} = 10 V, \\ I_D &= 10 A, \ R_G = 6 \Omega \end{split}$	
Turn-Off Delay Time	t <sub>D(OFF)</sub>	_	19.7				
Turn-Off Fall Time	t <sub>F</sub>		8.1		]		
Reverse Recovery Time	t <sub>RR</sub>	_	37.9	_	ns		
Reverse Recovery Charge	Q <sub>RR</sub>	_	51.9	_	nC	I <sub>F</sub> = 10A, di/dt = 100A/μs	

Notes: 5. Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.

6. Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.

7. Short duration pulse test used to minimize self-heating effect.

8. Guaranteed by design. Not subject to product testing.



T<sub>A</sub> I = 85°C 25°C

> Т -55°C

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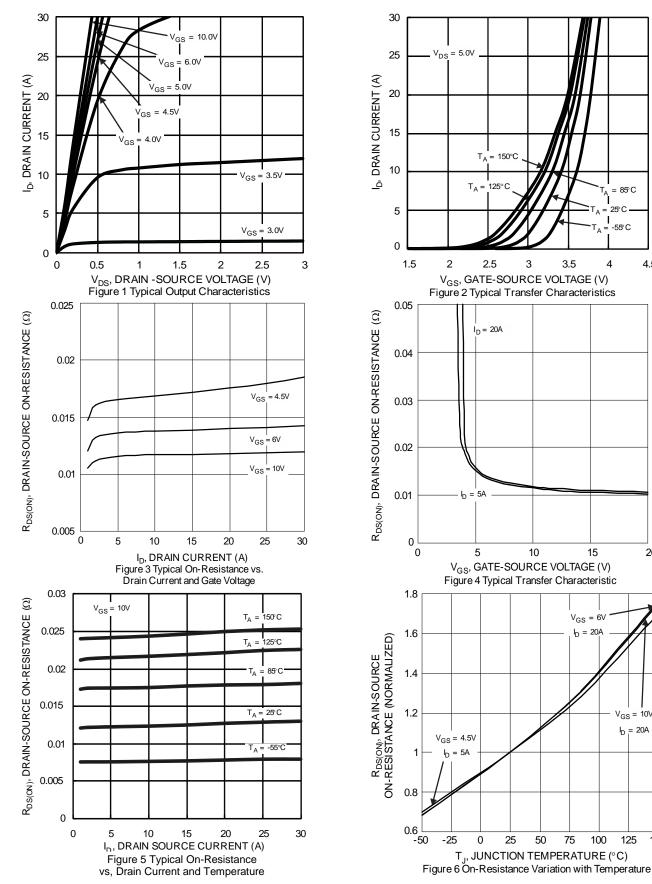
15

V<sub>GS</sub> = 6\

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 $V_{GS} = 10V$ I<sub>D</sub> = 20A

4.5

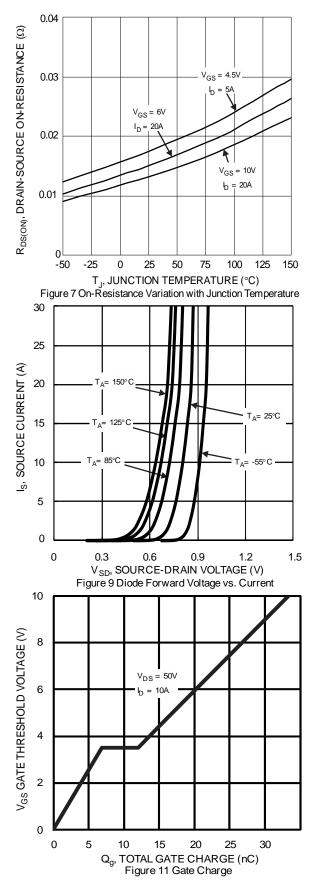


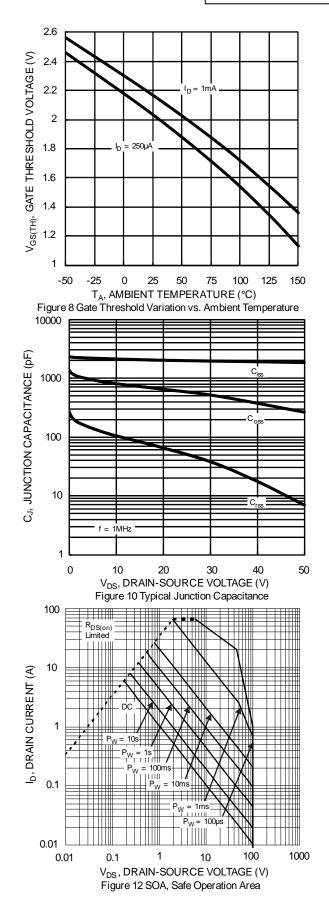
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125

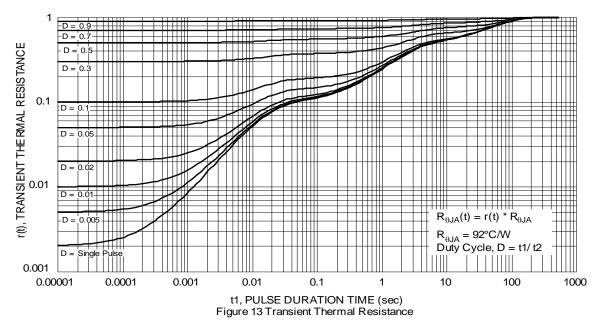
100







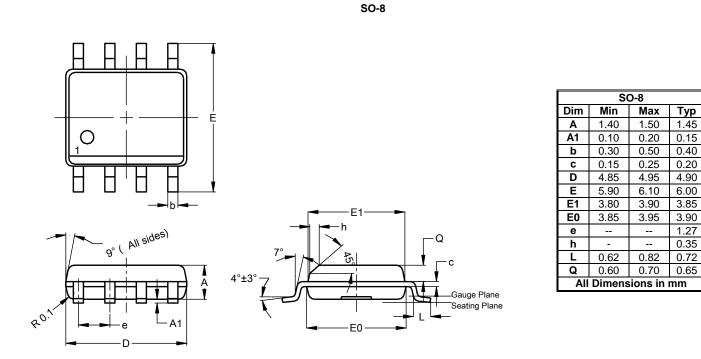






# **Package Outline Dimensions**

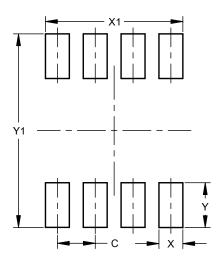
Please see http://www.diodes.com/package-outlines.html for the latest version.



SO-8

# **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.



n mm)
7
2
2
5
)



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